



Material Content Data Sheet



Sales Product Name				BSC014N06NST		Issued		23. January 2018	
MA#				MA001709016					
Package				PG-TDSON-8-17		Weight*		120.16 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.818	1.51	1.51	15134	15134	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		94		
	non noble metal	iron	7439-89-6	0.038	0.03		315		
	non noble metal	copper	7440-50-8	37.762	31.43	31.47	314268	314677	
	noble metal	gold	7440-57-5	0.044	0.04	0.04	370	370	
wire	organic material	carbon black	1333-86-4	0.129	0.11		1077		
encapsulation	plastics	epoxy resin	-	5.047	4.20		42002		
	inorganic material	silicondioxide	60676-86-0	37.959	31.59	35.90	315914	358993	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12081	12081	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1378	1378	
solder	non noble metal	tin	7440-31-5	0.050	0.04		415		
	noble metal	silver	7440-22-4	0.062	0.05		518		
heatspreader	non noble metal	lead	7439-92-1	2.380	1.98	2.07	19805	20738	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	zinc	7440-66-6	0.013	0.01		112		
	non noble metal	iron	7439-89-6	0.269	0.22		2236		
heat sink CLIP	non noble metal	copper	7440-50-8	10.909	9.08	9.31	90790	93166	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	zinc	7440-66-6	0.026	0.02		220		
	non noble metal	iron	7439-89-6	0.529	0.44		4403		
	non noble metal	copper	7440-50-8	21.482	17.88	18.35	178785	183463	
	*deviation < 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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